

INTERNATIONAL STANDARD

NORME INTERNATIONALE

**Surface mounting technology –
Part 3: Standard method for the specification of components for through hole
reflow (THR) soldering**

**Technique du montage en surface –
Partie 3: Méthode normalisée relative à la spécification des composants pour
le brasage par refusion à trous traversants (THR, Through Hole Reflow)**



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INTERNATIONAL ELECTROTECHNICAL COMMISSION

SURFACE MOUNTING TECHNOLOGY –

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International Standard IEC 61760-3 has been prepared by IEC technical committee 91: Electronics assembly technology.

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CDV	Report on voting
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Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

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